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Maximum Ratings (@T_A = +25°C unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	-12	V
Gate-Source Voltage			V_{GSS}	±8	V
Drain Current (Note 6)	Steady	T_A = +25°C	I_D	2	A

Thermal Characteristics

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P_D	0.48	W
Thermal Resistance, Junction to Ambient @T_A = +25°C (Note 5)	$R_{\theta JA}$	266	°C/W
Total Power Dissipation (Note 6)	P_D	1.26	W
Thermal Resistance, Junction to Ambient @T_A = +25°C (Note 6)	$R_{\theta JA}$	102	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	-12	—	—	V	V_{GS} = 0V, I_D = -250µA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	-1	µA	V_{DS} = -9.6V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±10	µA	V_{GS} = ±6V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(th)}$	-0.35	—	-1.0	V	V_{DS} = V_{GS}, I_D = -250µA
Static Drain-Source On-Resistance	$R_{DS\ (ON)}$	—	70 90 115 145	100 160 200 380	mΩ	V_{GS} = -4.5V, I_D = -2A V_{GS} = -2.5V, I_D = -1A V_{GS} = -1.8V, I_D = -0.5A V_{GS} = -1.5V, I_D = -0.2A
Forward Transfer Admittance	$\|Y_{fs}\|$	40	—	—	mS	V_{DS} = -5V, I_D = -0.5A
Diode Forward Voltage	V_{SD}	—	—	-1.2	V	V_{GS} = 0V, I_S = -0.2A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	514	—	pF	V_{DS} = -5V, V_{GS} = 0V, f = 1.0MHz
Output Capacitance	C_{oss}	—	131	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	60	—	pF	
Total Gate Charge	Q_g	—	5.8	—	nC	V_{GS} = -4.5V, V_{DS} = -5V, I_D = -2A
Gate-Source Charge	Q_{gs}	—	0.8	—	nC	
Gate-Drain Charge	Q_{gd}	—	1.2	—	nC	
Turn-On Delay Time	$t_{D(on)}$	—	15	—	nS	V_{DD} = -5V, V_{GEN} = -4.5V, R_{GEN} = 6Ω
Turn-On Rise Time	t_r	—	62	—	nS	
Turn-Off Delay Time	$t_{D(off)}$	—	332	—	nS	
Turn-Off Fall Time	t_f	—	166	—	nS	

Notes:
5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
6. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to production testing.

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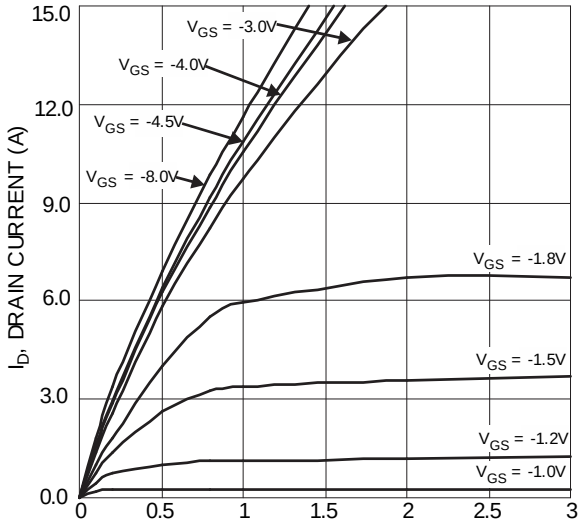

Figure 1 Typical Output Characteristics

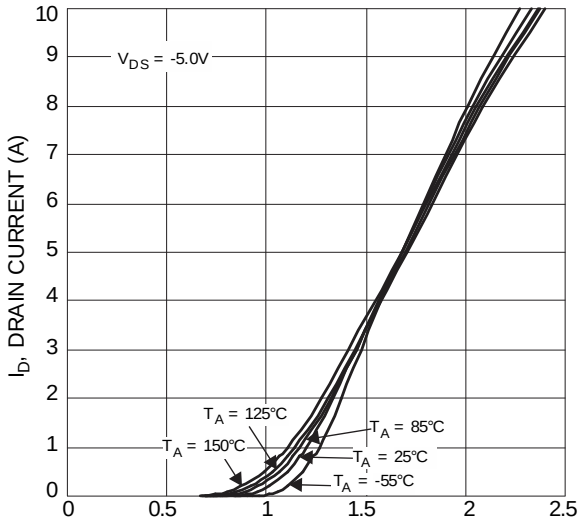

Figure 2 Typical Transfer Characteristics

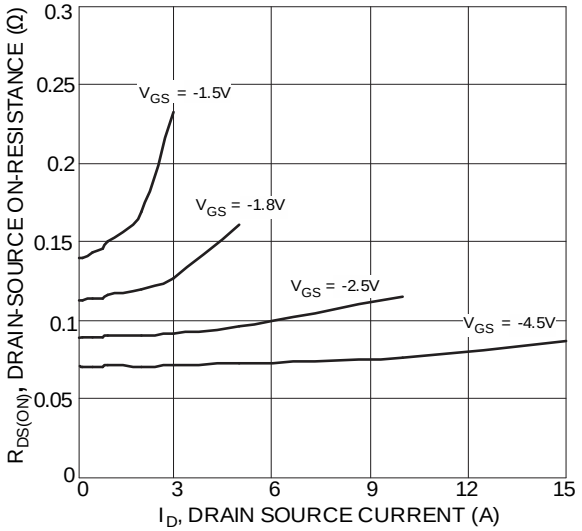

Figure 3 Typical On-Resistance vs.
Drain Current and Gate Voltage

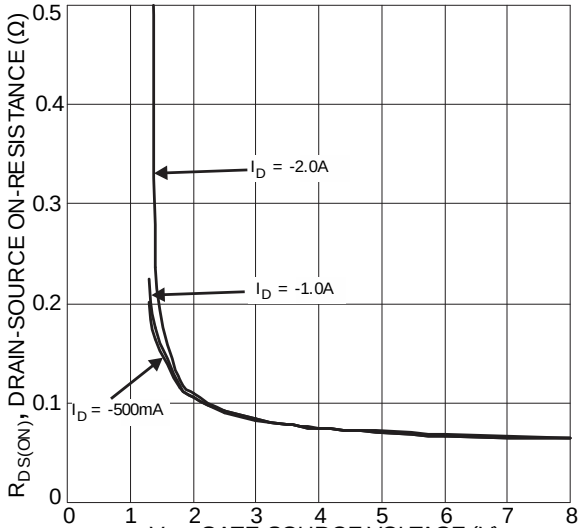

Figure 4 Typical Transfer Characteristic

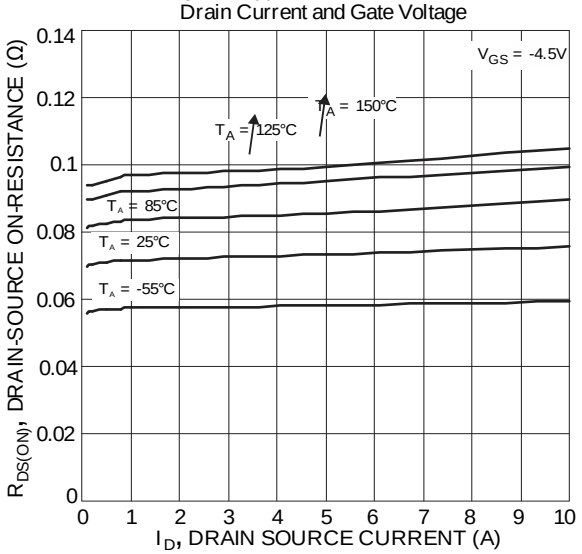

Figure 5 Typical On-Resistance vs.
Drain Current and Temperature

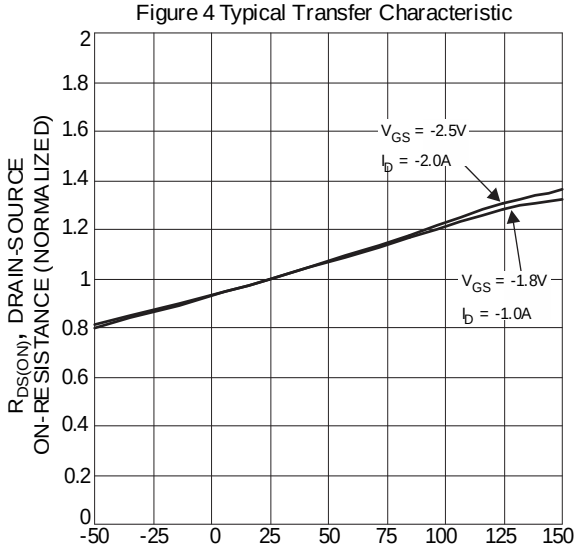

Figure 6 On-Resistance Variation with Temperature

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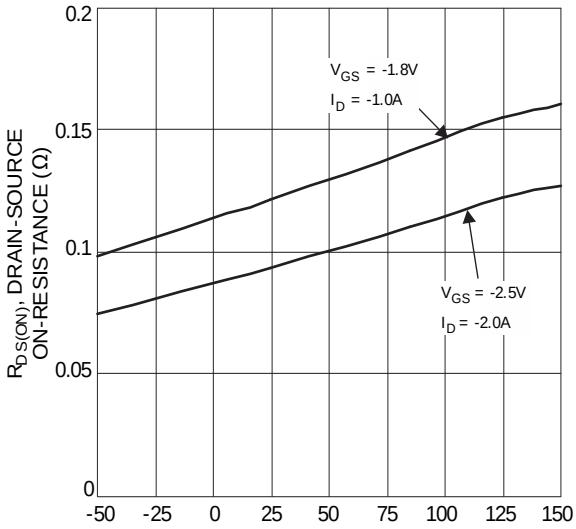

Figure 7 On-Resistance Variation with Temperature

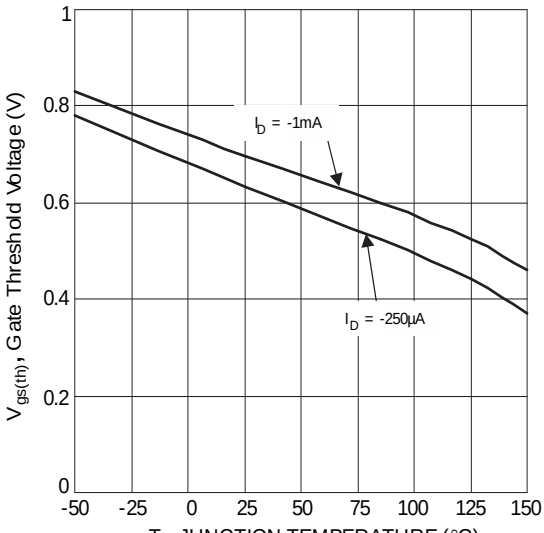

Figure 8 Gate Threshold Variation vs. Ambient Temperature

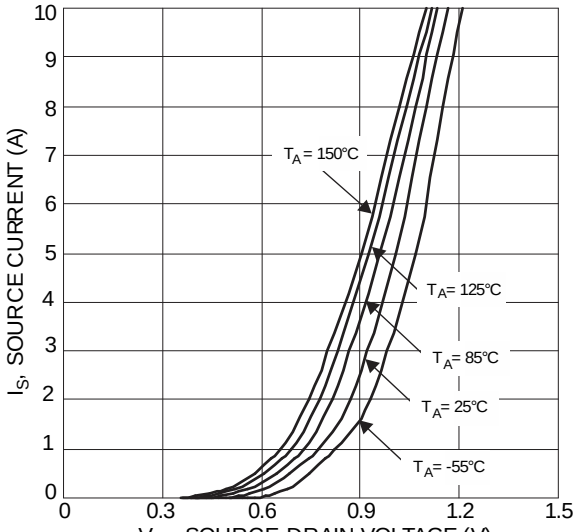

Figure 9 Diode Forward Voltage vs. Current

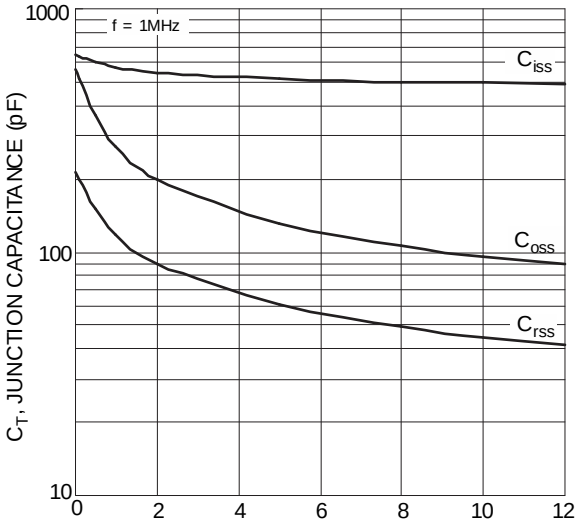

Figure 10 Typical Junction Capacitance

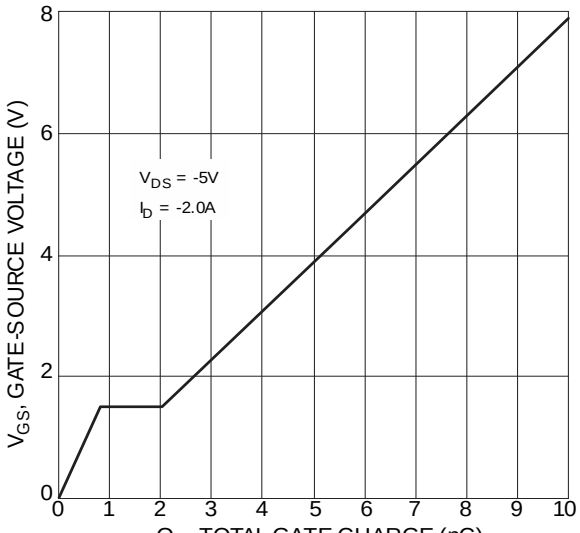

Figure 11 Gate-Charge Characteristics

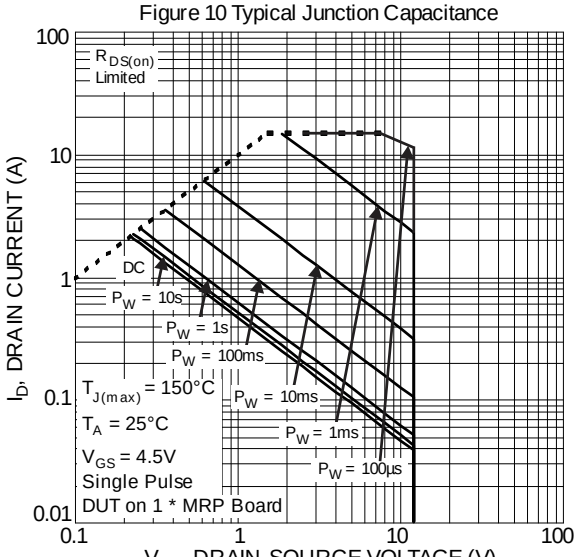

Figure 12 SOA, Safe Operation Area

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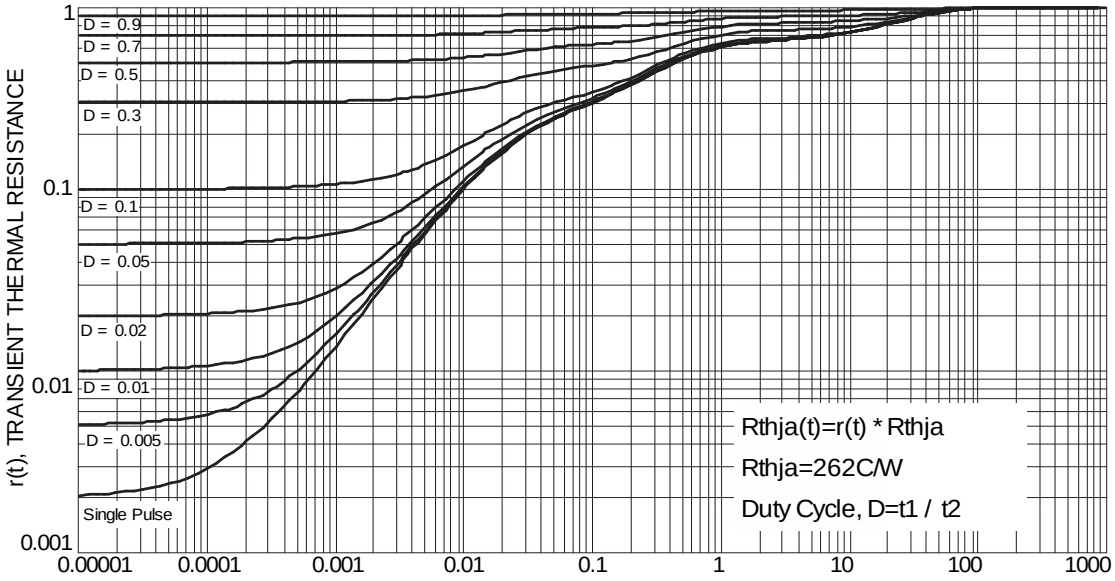
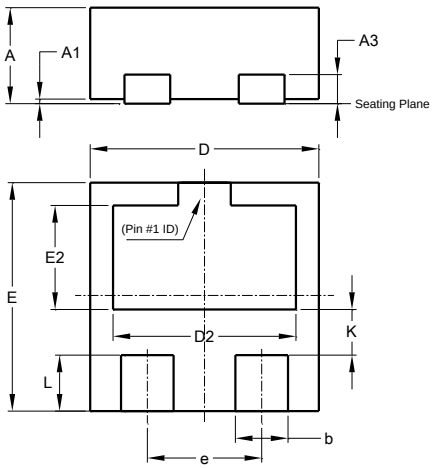


Figure 13 Transient Thermal Resistance

Package Outline Dimensions

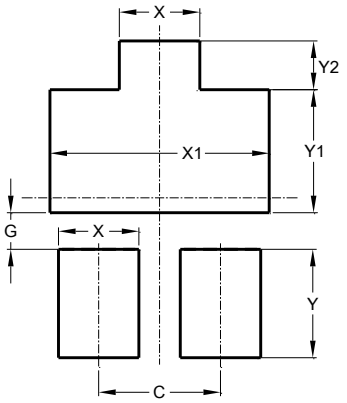
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X2-DFN1010-3			
Dim	**Min**	**Max**	**Typ**
A	-	0.40	0.39
A1	0.00	0.05	0.02
A3	-	-	0.13
b	0.18	0.28	0.23
D	0.95	1.05	1.00
D2	0.70	0.90	0.80
E	0.95	1.05	1.00
E2	0.36	0.56	0.46
e	-	-	0.50
K	-	-	0.20
L	0.195	0.295	0.245
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



X2-DFN1010-3	
Dimensions	**Value**
C	0.500
G	0.150
X	0.330
X1	0.900
Y	0.445
Y1	0.505
Y2	0.200
All Dimensions in mm	

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